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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>				ATTY. DOCKET NO. 007733 USA/FPS/MMCS/APC	SERIAL NO. 10/765,921	
				<b>APPLICANT</b> <b>Alexander T. SCHWARM</b>		
				FILING DATE January 29, 2004	GROUP	
<b>U.S. PATENT DOCUMENTS</b>						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	3,205,485	09/07/65	Noltingk	5,4		10/21/60
	3,229,198	01/11/66	Libby	9,1		09/28/62
	3,767,900	10/23/73	Chao et al.	7,9		06/23/71
	3,920,965	11/18/75	Sohrwardy	0,9		03/04/74
	4,000,458	12/28/76	Miller et al.	0,4		08/21/75
	4,207,520	06/10/80	Flora et al.	7,5		04/06/78
	4,209,744	06/24/80	Gerasimov et al.	9,7		03/27/78
	4,302,721	11/24/81	Urbanek et al.	2,7		05/15/79
	4,368,510	01/11/83	Anderson	3,5		10/20/80
	4,609,870	09/02/86	Lale et al.	9,8		09/13/84
	4,616,308	10/07/86	Morshedi et al.	5,31		12/02/85
	4,663,703	05/05/87	Axelby et al.	3,71		10/02/85
	4,698,766	10/06/87	Entwistle et al.	3,71		05/17/85
	4,750,141	06/07/88	Judell et al.	2,1		11/26/85
	4,755,753	07/05/88	Chern	5,7		07/23/86
	4,757,259	07/12/88	Charpentier	7,2		11/05/86
	4,796,194	01/03/89	Atherton	5,11		08/20/86
	4,901,218	02/13/90	Cornwell	1,2		03/04/88
	4,938,600	07/03/90	Into	3,61		02/09/89
	4,967,381	10/30/90	Lane et al.	7,3		07/06/89
	5,089,970	02/18/92	Lee et al.	1,9		10/05/89
	5,108,570	04/28/92	Wang	4,51		03/30/90
	5,208,765	05/04/93	Turnbull	4,71		07/20/90
	5,220,517	06/15/93	Sierk et al.	4,5		08/31/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
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Alexander T. SCHWARMFILING DATE  
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GROUP

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,270,222	12/14/93	Moslehi			12/31/90
	5,283,141	02/01/94	Yoon et al.			03/05/92
	5,295,242	03/15/94	Mashruwala et al.			11/02/90
	5,309,221	05/03/94	Fischer et al.			12/31/91
	5,329,463	07/12/94	Sierk et al.			01/13/93
	5,338,630	08/16/94	Yoon et al.			11/18/93
	5,347,446	09/13/94	Iino et al.			02/10/92
	5,367,624	11/22/94	Cooper			06/11/93
	5,375,064	12/20/94	Bollinger			12/02/93
	5,398,336	03/14/95	Tantry et al.			06/16/93
	5,402,367	03/28/95	Sullivan et al.			07/19/93
	5,408,405	04/18/95	Mozumder et al.			09/20/93
	5,410,473	04/25/95	Kaneko et al.			12/16/92
	5,420,796	05/30/95	Weling et al.			12/23/93
	5,427,878	06/27/95	Corliss			08/16/94
	5,469,361	11/21/95	Moyne			06/03/94
	5,485,082	01/16/96	Wisspeintner et al.			04/05/90
	5,490,097	02/06/96	Swenson et al.			08/06/93
	5,495,417	02/27/96	Fuduka et al.			03/16/93
	5,497,316	03/05/96	Sierk et al.			04/04/95
	5,497,381	03/05/96	O'Donoghue et al.			06/01/95
	5,503,707	04/02/96	Maung et al.			09/22/93
	5,508,947	04/16/96	Sierk et al.			05/13/94
	5,511,005	04/23/96	Abbe et al.			02/16/94
	5,519,605	05/21/96	Cawlfieid			10/24/94
	5,525,808	06/11/96	Irie et al.			12/20/94
	5,526,293	06/11/96	Mozumder et al.			12/17/93
▼	5,534,289	07/09/96	Bilder et al.			01/03/95
	5,541,510	07/30/96	Danielson			04/06/95

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,546,312	08/13/96	Mozumder et al.			02/24/94
	5,553,195	09/03/96	Meijer			09/29/94
	5,586,039	12/17/96	Hirsch et al.			02/27/95
	5,599,423	02/04/97	Parker et al.			06/30/95
	5,602,492	02/11/97	Cresswell et al.			04/28/94
	5,603,707	02/18/97	Trombetta et al.			11/28/95
	5,617,023	04/01/97	Skalski			02/02/95
	5,627,083	05/06/97	Tounai			05/12/95
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96
	5,649,169	07/15/97	Berezin et al.			06/20/95
	5,654,903	08/05/97	Reitman et al.			11/07/95
	5,655,951	08/12/97	Meikle et al.			09/29/95
	5,657,254	08/12/97	Sierk et al.			04/15/96
	5,661,669	08/26/97	Mozumder et al.			06/07/95
	5,663,797	09/02/97	Sandhu			05/16/96
	5,664,987	09/09/97	Renteln			09/04/96
	5,665,199	09/09/97	Sahota et al.			06/23/95
	5,666,297	09/09/97	Britt et al.			05/13/94
	5,667,424	09/16/97	Pan			09/25/96
	5,674,787	10/07/97	Zhao et al.			01/16/96
	5,694,325	12/02/97	Fukuda et al.			11/22/95
	5,698,989	12/16/97	Nulman			09/13/96
	5,719,495	02/17/98	Moslehi			06/05/96
	5,735,055	04/07/98	Hochbein et al.			04/23/96
	5,740,429	04/14/98	Wang et al.			07/07/95
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,751,582	05/12/98	Saxena et al.		05	09/24/96
	5,754,297	05/19/98	Nulman		05	04/14/97
	5,761,064	06/02/98	La et al.		06	10/06/95
	5,761,065	06/02/98	Kittler et al.		06	03/30/95
	5,764,543	06/09/98	Kennedy		06	06/16/95
	5,777,901	07/07/98	Berezin et al.		07	09/29/95
	5,787,021	07/28/98	Samaha		07	12/18/95
	5,808,303	09/15/98	Schlagheck et al.		09	01/29/97
	5,812,407	09/22/98	Sato et al.		09	08/12/97
	5,823,854	10/20/98	Chen		10	05/28/96
	5,825,913	10/20/98	Rostami et al.		10	07/18/95
	5,828,778	10/27/98	Hagi et al.		10	07/12/96
	5,832,224	11/03/98	Fehskens et al.		11	06/14/96
	5,838,595	11/17/98	Sullivan et al.		11	11/25/96
	5,844,554	12/01/98	Geller et al.		12	09/17/96
	5,857,258	01/12/99	Penzes et al.		01	05/12/94
	5,859,975	01/12/99	Brewer et al.		01	08/09/96
	5,862,054	01/19/99	Li		01	02/20/97
	5,863,807	01/26/99	Jang et al.		01	03/15/96
	5,867,389	02/02/99	Hamada et al.		02	11/26/96
	5,870,306	02/09/99	Harada		02	06/13/97
	5,883,437	03/16/99	Maruyama et al.		03	12/28/95
	5,889,991	03/30/99	Consolatti et al.		03	12/06/96
	5,901,313	05/04/99	Wolfe et al.		05	09/02/97
	5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96
▼	5,910,011	06/08/99	Cruse			05/12/97
	5,910,846	06/08/99	Sandhu			08/19/97
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	5,912,678	06/15/99	Saxena et al.		15/4	04/14/97
	5,916,016	06/29/99	Bothra		29/4	10/23/97
	5,923,553	07/13/99	Yi		13/4	10/05/96
	5,926,690	07/20/99	Toprac et al.		10/4	05/28/97
	5,930,138	07/27/99	Lin et al.		17/4	09/10/97
	5,940,300	08/17/99	Ozaki		17/4	05/08/97
	5,943,237	08/24/99	Van Boxem		24/4	10/17/97
	5,960,214	09/28/99	Sharpe, Jr. et al.		18/4	12/04/96
	5,961,369	10/05/99	Bartels et al.		15/4	06/04/98
	5,963,881	10/05/99	Kahn et al.		15/4	10/20/97
	5,978,751	11/02/99	Pence et al.		24/4	02/25/97
	5,982,920	11/09/99	Tobin, Jr. et al.		9/4	01/08/97
	6,002,989	12/14/99	Shiba et al.		4/4	04/01/97
	6,017,771	01/25/00	Yang et al		3/4	04/27/98
	6,036,349	03/14/00	Gombar		4/4	07/26/96
	6,041,263	03/21/00	Boston et al.		17/4	10/01/97
	6,041,270	03/21/00	Steffan et al.		17/4	12/05/97
	6,054,379	04/25/00	Yau et al.		5/4	02/11/98
	6,064,759	05/16/00	Buckley et al.		6/4	11/06/97
	6,072,313	06/06/00	Li et al.		5/4	06/17/97
	6,074,443	06/13/00	Venkatesh et al.		3/4	01/29/98
	6,077,412	06/20/00	Ting et al.		3/4	10/30/98
	6,078,845	06/20/00	Friedman		11/4	11/25/96
	6,094,688	07/25/00	Mellen-Garnett et al.		3/4	03/12/98
	6,097,887	08/01/00	Hardikar et al.			10/27/97
	6,108,092	08/22/00	Sandhu			06/08/99
	6,111,634	08/29/00	Pecen et al.			05/28/97
▼	6,112,130	08/29/00	Fukuda et al.			10/01/97

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,127,263	10/03/00	Parikh		13/0	07/10/98
	6,128,016	10/03/00	Coelho et al.		13/0	12/20/96
	6,136,163	10/24/00	Cheung et al.		24/0	03/05/99
	6,141,660	10/31/00	Bach et al.		31/0	07/16/98
	6,143,646	11/07/00	Wetzel		17/0	06/03/97
	6,148,099	11/14/00	Lee et al.		4/0	07/03/97
	6,148,239	11/14/00	Funk et al.		4/0	12/12/97
	6,148,246	11/14/00	Kawazome		4/0	06/10/98
	6,150,664	11/21/00	Su		11/0	06/29/99
	6,159,075	12/12/00	Zhang		2/0	10/13/99
	6,159,644	12/12/00	Satoh et al.		2/0	03/06/96
	6,161,054 B1	12/12/00	Rosenthal et al.		2/0	09/17/98
	6,169,931 B1	01/02/01	Runnels		2/0	07/29/98
	6,172,756 B1	01/09/01	Chalmers et al.		9/0	12/11/98
	6,173,240 B1	01/09/01	Sepulveda et al.		19/0	11/02/98
	6,175,777 B1	01/16/01	Kim		6/0	01/16/98
	6,178,390 B1	01/23/01	Jun		3/0	09/08/98
	6,183,345 B1	02/06/01	Kamono et al.		6/0	03/20/98
	6,185,324 B1	02/06/01	Ishihara et al.		5/0	01/31/95
	6,191,864 B1	02/20/01	Sandhu		3/0	02/29/00
	6,192,291 B1	02/20/01	Kwon		3/0	10/08/98
	6,197,604 B1	03/06/01	Miller et al.		5/0	10/01/98
	6,204,165 B1	03/20/01	Ghoshal		5/0	06/24/99
	6,211,094 B1	04/03/01	Jun et al.		5/0	08/23/99
	6,214,734 B1	04/10/01	Bothra et al.			11/20/98
	6,217,412 B1	04/17/01	Campbell et al.			08/11/99
	6,219,711 B1	04/17/01	Chari			10/01/97
	6,222,936 B1	04/24/01	Phan et al.			09/13/99

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	6,226,792 B1	05/01/01	Goiffon et al.	C		10/14/98
	6,230,069 B1	05/08/01	Campbell et al.	C		06/26/98
	6,236,903 B1	05/22/01	Kim et al.	C		09/25/98
	2001/0001755 A1	05/24/01	Sandhu et al.	C		12/29/00
	6,240,330 B1	05/29/01	Kurtzberg et al.	C		05/28/97
	6,240,331 B1	05/29/01	Yun	C		08/18/98
	2001/0003084 A1	06/07/01	Finarov	C		12/04/00
	6,245,581 B1	06/12/01	Bonser et al.	C		04/19/00
	6,246,972 B1	06/12/01	Klimasauskas	C		05/27/99
	6,248,602 B1	06/19/01	Bode et al.	C		11/01/99
	6,249,712 B1	06/19/01	Boiquaye	C		09/25/96
	6,252,412 B1	06/26/01	Talbot et al.	C		01/08/99
	6,253,366 B1	06/26/01	Mutschler, III	C		03/31/99
	6,263,255 B1	07/17/01	Tan et al.	C		05/18/98
	6,271,670 B1	08/07/01	Caffey	C		02/08/99
	6,276,989 B1	08/21/01	Campbell et al.	C		08/11/99
	6,278,899 B1	08/21/01	Piche et al.	C		10/06/99
	6,280,289 B1	08/28/01	Wiswesser et al.	C		11/02/98
	6,284,622 B1	09/04/01	Campbell et al.	C		10/25/99
	6,287,879 B1	09/11/01	Gonzales et al.	C		08/11/99
	6,290,572 B1	09/18/01	Hofmann	C		03/23/00
	6,292,708 B1	09/18/01	Allen et al.	C		06/11/98
	6,298,274 B1	10/02/01	Inoue	C		09/01/99
	6,298,470 B1	10/02/01	Breiner et al.	C		04/15/99
	6,303,395 B1	10/16/01	Nulman	C		06/01/99
	6,304,999 B1	10/16/01	Toprac et al.	C		10/23/00
	2001/0030366 A1	10/18/01	Nakano et al.	C		03/07/01
▼	6,307,628 B1	10/23/01	Lu et al.	C		08/18/00
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	2001/0039462 A1	11/08/01	Mendez et al.	1		04/02/01
	2001/0040997 A1	11/15/01	Tsap et al.	1		05/15/01
	6,320,655 B1	11/20/01	Matsushita et al.	10		03/15/00
	2001/0042690 A1	11/22/01	Talieh	11		12/14/00
	2001/0044667 A1	11/22/01	Nakano et al.	11		05/16/01
	6,324,481 B1	11/27/01	Atchison et al.	4		06/15/99
	6,334,807 B1	01/01/02	Lebel et al.	4		04/30/99
	6,336,841 B1	01/08/02	Chang	5		03/29/01
	6,340,602 B1	01/22/02	Johnson et al.	10		02/12/01
	6,345,288 B1	02/05/02	Reed et al.	5		05/15/00
	6,345,315 B1	02/05/02	Mishra	5		08/12/98
	6,346,426 B1	02/12/02	Toprac et al.	5		11/17/00
	2002/0032499	03/14/02	Wilson et al.	10		05/04/01
	6,360,133 B1	03/19/02	Campbell et al.	10		06/17/99
	6,363,294 B1	03/26/02	Coronel et al.	3		12/29/98
	6,366,934 B1	04/02/02	Cheng et al.	3		06/02/99
	6,368,879 B1	04/09/02	Toprac	3		09/22/99
	6,368,883 B1	04/09/02	Bode et al.	3		08/10/99
	6,368,884 B1	04/09/02	Goodwin et al.	3		04/13/00
	6,379,980 B1	04/30/02	Toprac	3		07/26/00
	6,388,253 B1	05/14/02	Su	3		11/02/00
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			APPLICANT Alexander T. SCHWARM			
			FILING DATE January 29, 2004		GROUP	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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<b>U.S. PATENT DOCUMENTS</b>						
EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
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▼	09/998,384	11/30/01	Paik	Feedforward and Feedback Control for Conditioning of Chemical Mechanical Polishing Pad		
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	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
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↓	10/759,108	01/20/04	Schwarm	Automated Design and Execution of Experiments with Integrated Model Creation for Semiconductor Manufacturing Tools			
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						Yes	No
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	61-171147	08/01/86	Japan			X	spa
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	05-266029 ✓	10/15/93	Japan			X	par
	06-110894	04/22/94	Japan			X	par
	06-176994	06/24/94	Japan			X	par
	06-184434 ✓	07/05/94	Japan			X	par
	06-252236 ✓	09/09/94	Japan			X	par
	06-260380 ✓	09/16/94	Japan			X	par
	EP 0 621 522 A2 ✓	10/26/94	Europe			X	par
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	08-50161 ✓	02/20/96	Japan			X	par
	08-149583 ✓	06/07/96	Japan			X	par
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	WO 98/45090	10/15/98	WO			X	ope
	EP 0 877 308 A2	11/11/98	Europe			X	ope
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	WO 99/25520	05/27/99	WO			X	ope
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	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 10%;"></td> <td>Scarr, J. M. and J. K. Zelisse. April 1993. "New Topology for Thickness Monitoring Eddy Current Sensors (Abstract)." <i>Proceedings of the 36<sup>th</sup> Annual Technical Conference</i>, Dallas, Texas.</td> </tr> <tr> <td></td> <td>Hu, Albert, Kevin Nguyen, Steve Wong, Xiuhua Zhang, Emanuel Sachs, and Peter Renteln. 1993. "Concurrent Deployment of Run by Run Controller Using SCC Framework." <i>IEEE/SEMI International Semiconductor Manufacturing Science Symposium</i>. pp. 126-132.</td> </tr> <tr> <td></td> <td>Matsuyama, Akira and Jessi Niou. 1993. "A State-of-the-Art Automation System of an ASIC Wafer Fab in Japan." <i>IEEE/SEMI International Semiconductor Manufacturing Science Symposium</i>, pp. 42-47.</td> </tr> <tr> <td></td> <td>Yeh, C. Eugene, John C. Cheng, and Kwan Wong. 1993. "Implementation Challenges of a Feedback Control System for Wafer Fabrication." <i>IEEE/CHMT International Electronics Manufacturing Technology Symposium</i>, pp. 438-442.</td> </tr> <tr> <td></td> <td>Kurtzberg, Jerome M. and Menachem Levanoni. January 1994. "ABC: A Better Control for Manufacturing." <i>IBM Journal of Research and Development</i>, v. 38, n. 1, pp. 11-30.</td> </tr> <tr> <td></td> <td>Mozumder, Purnendu K. and Gabriel G. Barna. February 1994. "Statistical Feedback Control of a Plasma Etch Process." <i>IEEE Transactions on Semiconductor Manufacturing</i>, v. 7, n. 1, pp. 1-11.</td> </tr> <tr> <td></td> <td>Muller-Heinzerling, Thomas, Ulrich Neu, Hans Georg Nurnberg, and Wolfgang May. March 1994. "Recipe-Controlled Operation of Batch Processes with Batch X." <i>ATP Automatisierungstechnische Praxis</i>, vol. 36, no. 3, pp. 43-51.</td> </tr> <tr> <td></td> <td>Stoddard, K., P. Crouch, M. Kozicki, and K. Tsakalis. June-July 1994. 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EXAMINER <i>Sean Shechtman</i> / (09/21/2006)						
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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>   (PTO-1449)		ATTY. DOCKET NO. 007733 USA/ FPS/MMCS/APC	SERIAL NO. 10/765,921
<b>APPLICANT</b> Alexander T. SCHWARM			
<b>FILING DATE</b> January 29, 2004		<b>GROUP</b> 2125	
<b>OTHER ART</b> (Including Author, Title, Date, Pertinent Pages, Etc.)			
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